

**Amendments to the Claims:**

The listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

1. (currently amended): A system for integrating circuitry on an isolation layer, comprising:

a plurality of isolation substrates, each isolation substrate having a circuit deposition region and a substrate-combining region;

a plurality of circuits formed on the circuit deposition regions;

a plurality of substrate-connecting elements formed to connect the substrate-combining regions; and

a plurality of electrical connecting elements formed to electrically connect the circuits formed on the different circuit deposition regions, wherein the circuit deposition region contacts the substrate-combining region on ~~different planes~~ more than one face thereof, and wherein at least two isolation substrates contact at respective substrate-combining regions.

2. (original): The system as claimed in claim 1, wherein the substrate-connecting elements are formed by heat fusing or laser.

3. (original): The system as claimed in claim 1, wherein the electrical connecting elements are flex print cables or gold lines.

4. (original): The system as claimed in claim 1, wherein the electrical connecting elements are formed by laser fusing.

5. (original): The system as claimed in claim 1, wherein the materials of the isolation substrates are different.

6. (canceled)

7. (original): The system as claimed in claim 1, wherein the materials of the isolation substrates are plastic or glass.

8. (Previously presented): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate including a first circuit deposition region and a first substrate-combining region, and a second isolation substrate including a second circuit deposition region and a second substrate-combining region;

forming a first circuit and a second circuit respectively on the first circuit deposition region and the second circuit deposition region;

contacting the first substrate-combining region and the second substrate-combining region;

forming a plurality of substrate-connecting elements for connecting the first substrate-combining region to the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the first circuit and the second circuit.

9. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the substrate-connecting elements are formed by heat fusing or laser.

10. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are flex print cables or gold lines.

11. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are formed by laser fusing.

12. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the first circuit and the second circuit are packed by different packaging methods.

13. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate is plastic.

14. (Original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate are glass.

15. (Original): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate and a second isolation substrate respectively including a first circuit deposition region and a second circuit deposition region;

forming a plurality of first circuits and a plurality of second circuits respectively on the first circuit deposition region and the second circuit deposition region;

cutting the first isolation substrate and the second isolation substrate, wherein the cut first isolation substrate comprises single first circuit and a first substrate-combining region, and the cut second isolation substrate comprises a single second circuit and a second substrate-combining region;

forming a plurality of substrate-connecting elements for connecting the cut first isolation substrate to the cut second isolation substrate, wherein the first substrate-combining region contacts the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the single first circuit and the single second circuit.

16. (Original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the substrate-connecting elements are formed by heat fusing or laser.

17. (Original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are flex print cables or gold lines.

18. (Original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are formed by laser fusing.

19. (Original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the first isolation substrate is plastic.

20. (Original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the second isolation substrate is glass.

21. (currently amended): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate including a first circuit deposition region and a first substrate-combining region, and a second isolation substrate including a second circuit deposition region and a second substrate-combining region, wherein the materials of the first and second isolation substrates are different;

forming a first circuit and a second circuit respectively on the first circuit deposition region and the second circuit deposition region, ~~wherein the first circuit and the second circuit are packed by different packaging methods;~~

forming a plurality of substrate-connecting elements for connecting the first substrate-combining region to the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the first circuit and the second circuit.